

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

OSAMU FURUKAWA, ET AL. : GROUP UNIT:

SERIAL NO: NEW DIV. APPLN. :

FILED: HEREWITH : EXAMINER:

FOR: ELECTRONIC COMPONENT AND :  
METHOD OF PRODUCTION THEREOF

PRELIMINARY AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

SIR:

Prior to initial examination on the merits, please amend the above-identified application as follows:

IN THE CLAIMS

Please cancel Claims 1-165 without prejudice or disclaimer.

Please add new Claims 166-171 as follows:

--166. A surface acoustic wave device, comprising:

a printed circuit board possessing a first board surface and a second board surface, the first board surface having a board wiring pattern and a board wiring pad which is thicker than the board wiring pattern;

a surface acoustic wave element possessing a first element surface and a second element surface, the first element surface including a transducer portion, an element wiring pad, and a surface acoustic wave absorbing member formed outside of the element wiring pad, and the first element surface being disposed in an opposite relation with respect to the first board surface; and

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a conductive connecting member disposed between the board wiring pad and the element wiring pad.

167. The surface acoustic wave device as set forth in Claim 166, wherein a difference between a thickness of the board wiring pattern and a thickness of the board wiring pad is in the range of from 5  $\mu\text{m}$  to 100  $\mu\text{m}$ .

168. A surface acoustic wave device, comprising:

a printed circuit board possessing a first region and a second region which is larger in thickness than the first region, the second region including a board wiring pad;

a surface acoustic wave element possessing a first element surface and a second element surface, the first element surface including a transducer portion, an element wiring pad and a surface acoustic wave absorbing member, and being disposed with a face-down arrangement so that the surface acoustic wave absorbing member is disposed in an opposite relation with respect to the first region of the printed circuit board; and

a conductive connecting member disposed between the board wiring pad and the element wiring pad.

169. The surface acoustic wave device as set forth in Claim 168 wherein a difference between a thickness of the first region and a thickness of the second region of the printed circuit board is in the range of from 5  $\mu\text{m}$  to 500  $\mu\text{m}$ .

170. A surface acoustic wave device, comprising:

a printed circuit board possessing a first board surface and a second board surface, the first board surface having a board wiring pattern;

a surface acoustic wave element possessing a first element surface and a second element surface, the first element surface including a transducer portion, an element wiring pad and a

surface acoustic wave absorbing member, and the first element surface being disposed in an opposite relation with respect to the first board surface; and

a conductive connecting member disposed between the board wiring pattern and the element wiring pad, the conductive connecting member being composed of a plurality of bumps stacked according to a spacing between the board wiring pattern and the element wiring pad.

171. The surface acoustic wave device as set forth in Claim 170, wherein a thickness of the conductive connecting member is larger than a thickness of the surface acoustic wave absorbing member.--

REMARKS

Favorable consideration of this application is respectfully requested.

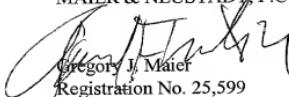
Claims 166-171 are presently active in this application. Original Claims 1-165 have been canceled without prejudice or disclaimer.

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In light of the above, an early and favorable examination on the merits as to the presently active Claims 166-171 is respectfully requested.

Respectfully submitted,

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